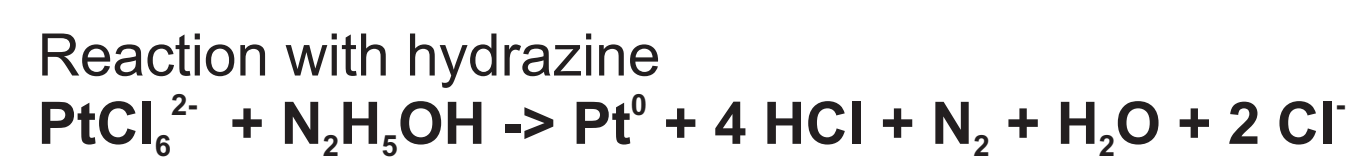
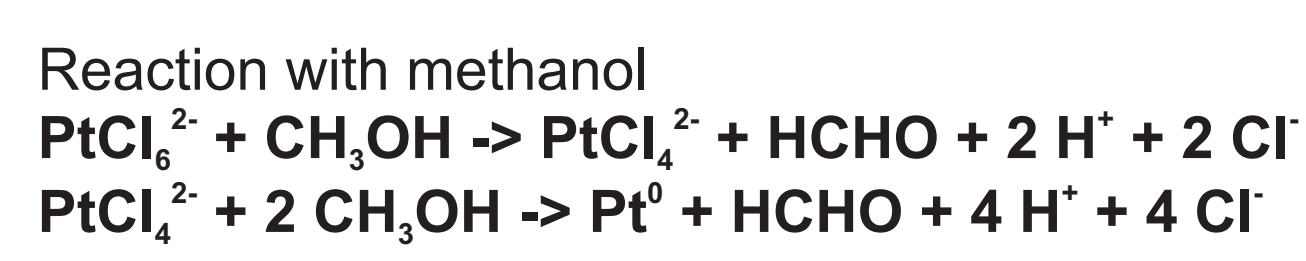


## Abstract

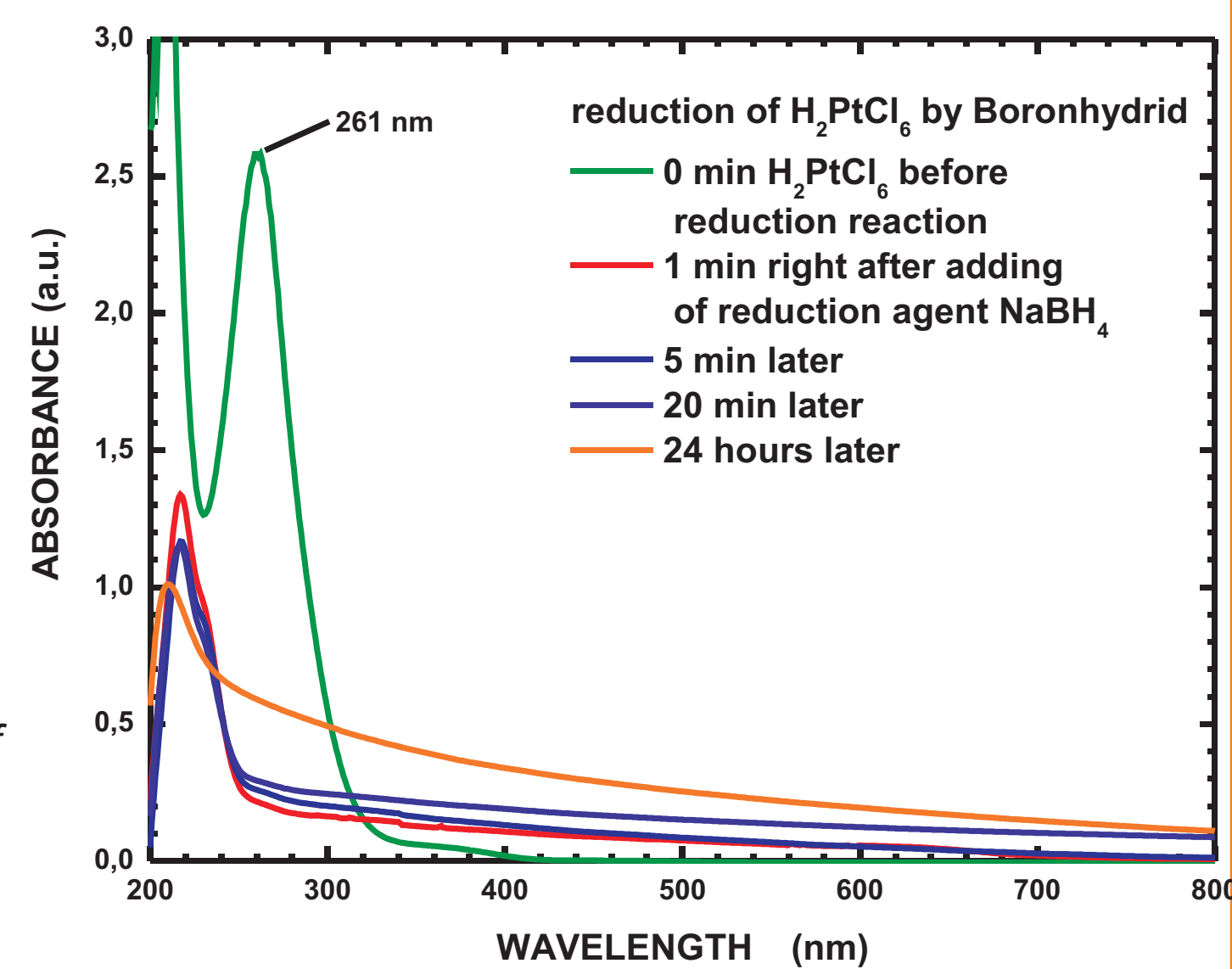
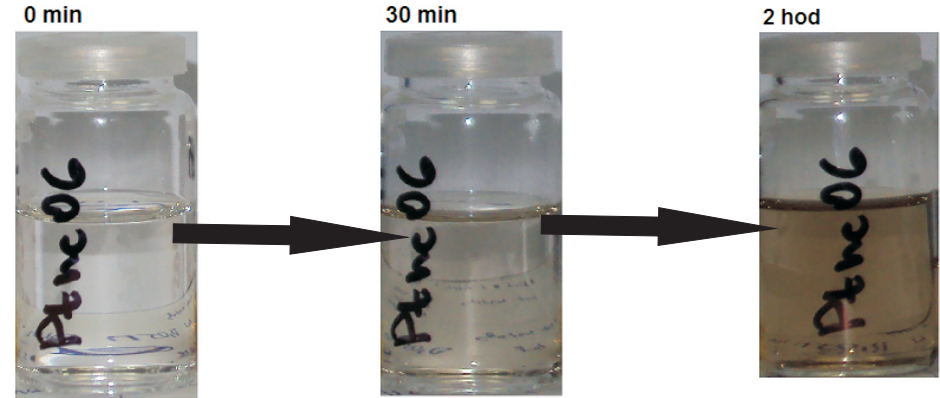
In this work, colloid solutions of metal Pt and Pd nanoparticles both by direct reduction of metal salts in water solutions and by reverse micelle technique were prepared. Layers of the nanoparticles on InP and GaN substrates using electrophoretic deposition were prepared. Metal nanoparticles in the colloid and deposited metal nanoparticles on semiconductor surface were characterised by SEM. Schottky diodes were fabricated by application of colloidal graphite or silver paste on nanoparticle layer. Diodes exhibited excellent current–voltage rectifying characteristics. Schottky barrier height of 1.03 eV was calculated for GaN/Pd structure and 0.78 eV for InP/Pd structure. A rapid increase in current under the flow of H<sub>2</sub>/N<sub>2</sub> was observed and measured for different hydrogen concentration and voltage applied on diode.

## Metal nanoparticles in water solutions

Reduction of H<sub>2</sub>PtCl<sub>6</sub> and PdCl<sub>2</sub> by hydrazine, boronhydride or methanol



Reduction reaction is very fast, followed by nucleation and growth of nanoparticles. Stabilisation of colloidal solution is provided by citrate ions. Growth of palladium and platinum nanoparticles is connected with change of color of solution from colourless into brown.

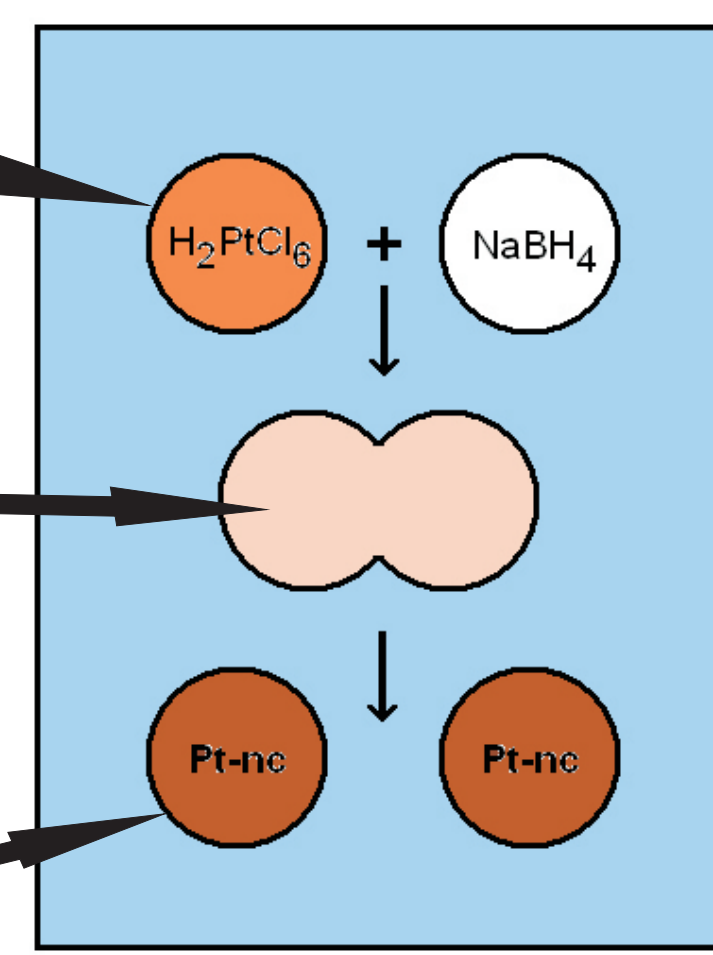


## Metal nanoparticles in water-in-oil microemulsions

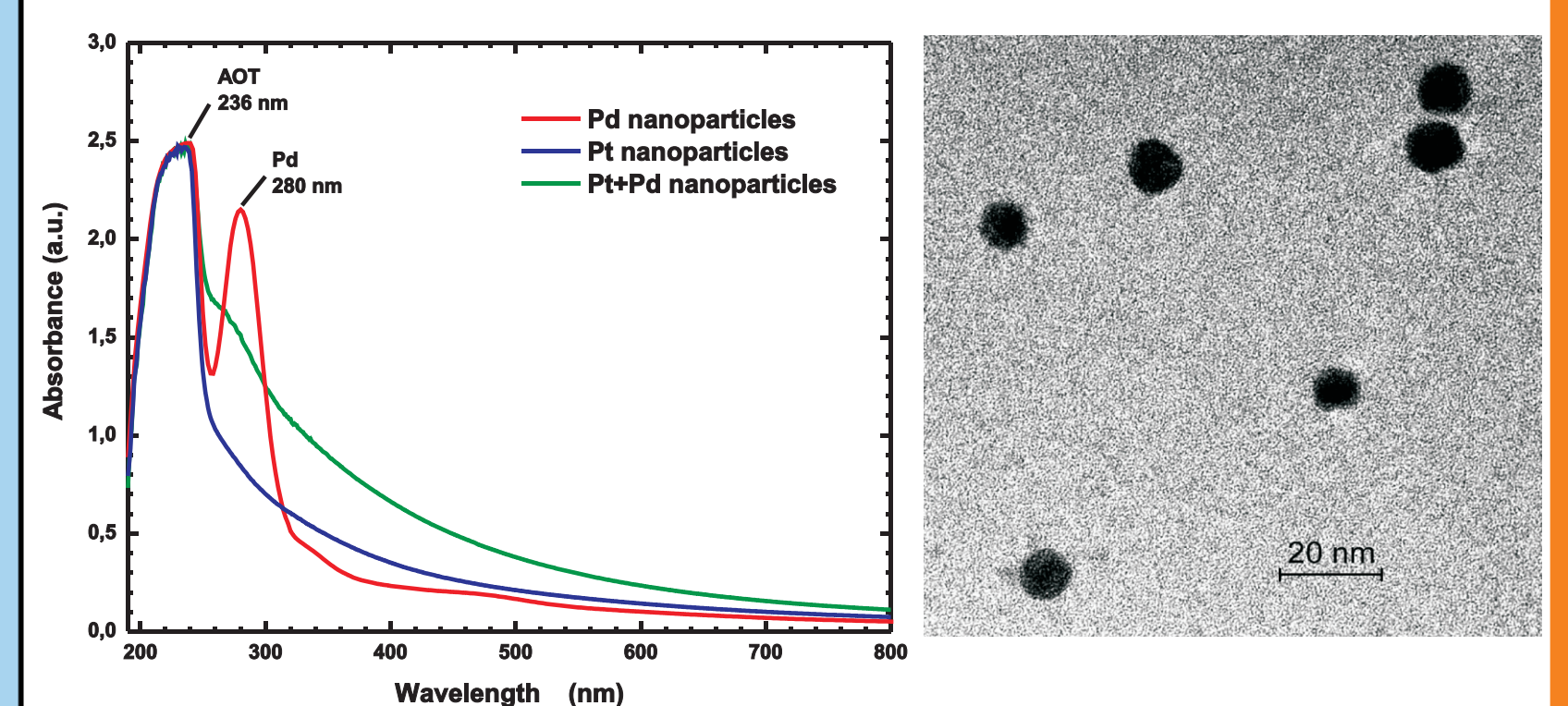
Mixing of two solutions of reverse micelles  
 -one solution with metal ions  
 -one solution with reducing agent

Exchanging of reverse micelle contents due to their mutual collisions

Formation of nucleation center and growth of metal nanoparticles



Reverse micelles: surfactant AOT in isoctane → diameter controlled and monodisperse metal nanoparticles



The diameter of nanoparticles is 10 nm when the ratio of molar concentrations of AOT and water content is equal to 5. UV–VIS absorption spectra shows a peak at 280 nm due to plasmon absorption by palladium particles and a peak at 220–240 nm due to AOT absorption.

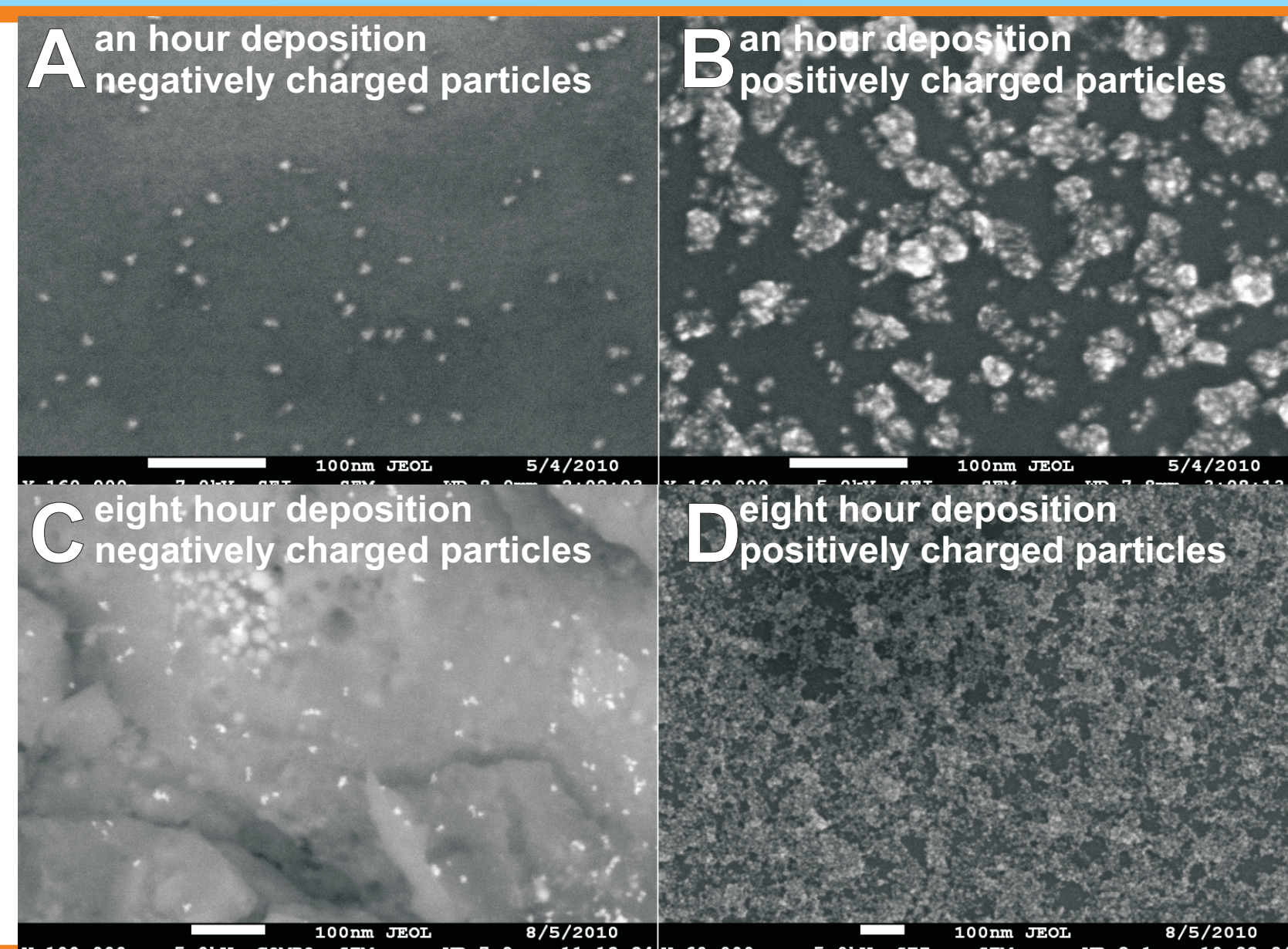
## Electrophoretic deposition

two–electrode cell: semiconductor wafer is connected to one electrode, the cell is filled by microemulsion of metal nanoparticles in isoctane and the voltage in order of tens of volts is applied.

Pictures A and B show an hour deposition of Pt nanoparticles in AOT reverse micelles. The semiconductor wafer was connected to a positive electrode in the case of the pic. A and to a negative electrode in the case of the pic. B. It is clearly seen, that metal nanoparticles in solution are mostly positively charged.

Pictures C and D show eight hour deposition of Pt nanoparticles under same voltage polarity as pictures above. Longer deposition on negative electrode leads to higher coverage by metal nanoparticles whereas longer deposition on positive electrode leads to higher coverage by organic material from reverse micelle solution.

Situation B gives the best current–voltage characteristics and hydrogen sensitivity.



## Current-Voltage characteristics

A potential barrier arises at the interface of metal nanoparticle and semiconductor wafer. Current–voltage (IV) characteristics is given by thermionic–emission–diffusion theory. Current density depends on temperature, Schottky barrier height and voltage by equation

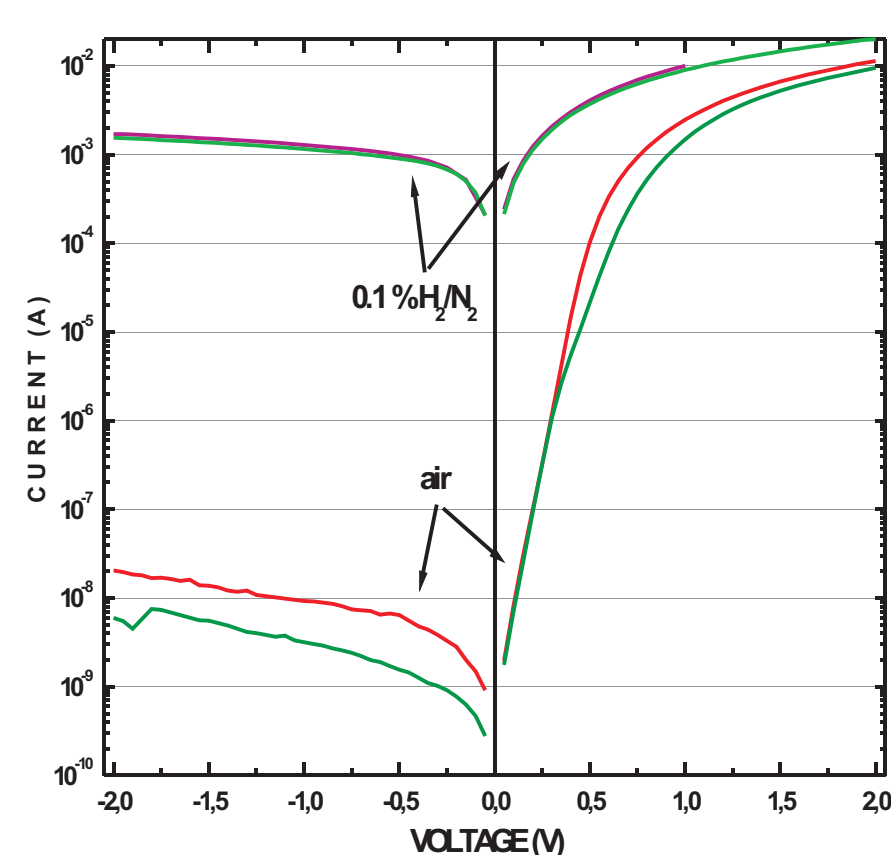
$$j(V) = A^{**} T^2 e^{-\frac{e\phi_B}{kT}} e^{\frac{eV}{kT}} - 1$$

## Hydrogen detection

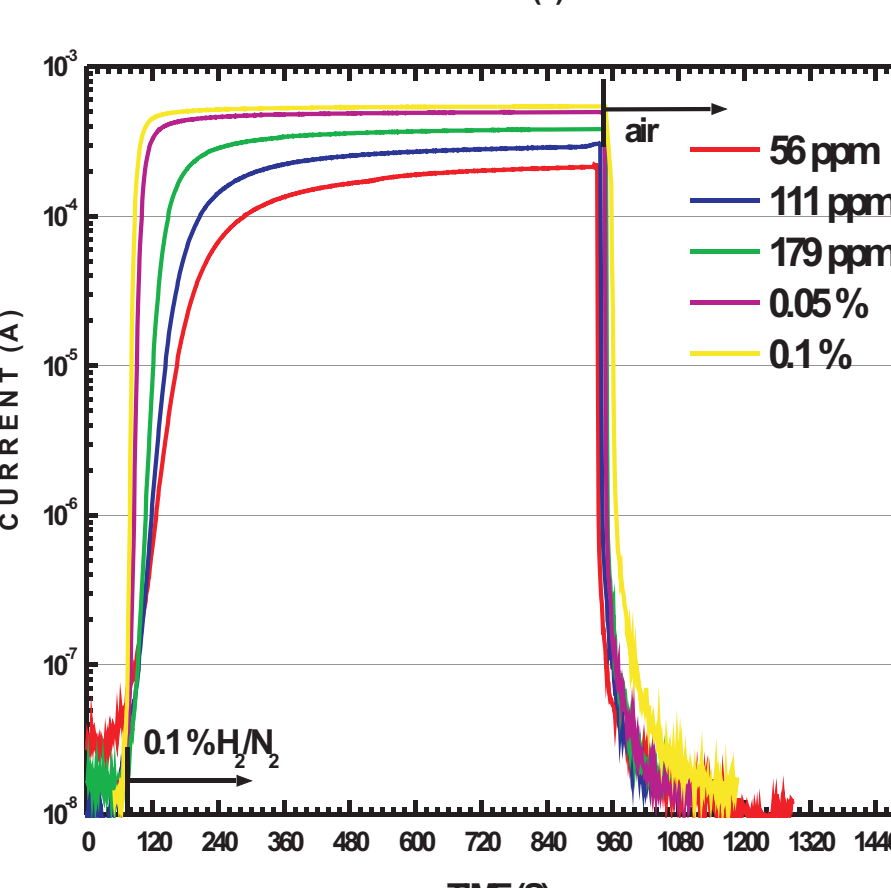
Hydrogen molecule is dissociated by the palladium or platinum nanoparticles, single hydrogen atoms are absorbing by nanoparticles. These hydrogen atoms get into nanoparticle–semiconductor interface and create a dipole layer which decreases the Schottky barrier height. The barrier decrease is measured as an increase in current.

## Pt nanoparticles based structures

Forward and reverse IV characteristics of two diodes on GaN substrate with a layer of platinum nanoparticles in air and hydrogen environment. Both diodes show good rectifying character in air ambience. The height of Schottky barrier calculated from the forward current is 0.81 eV.

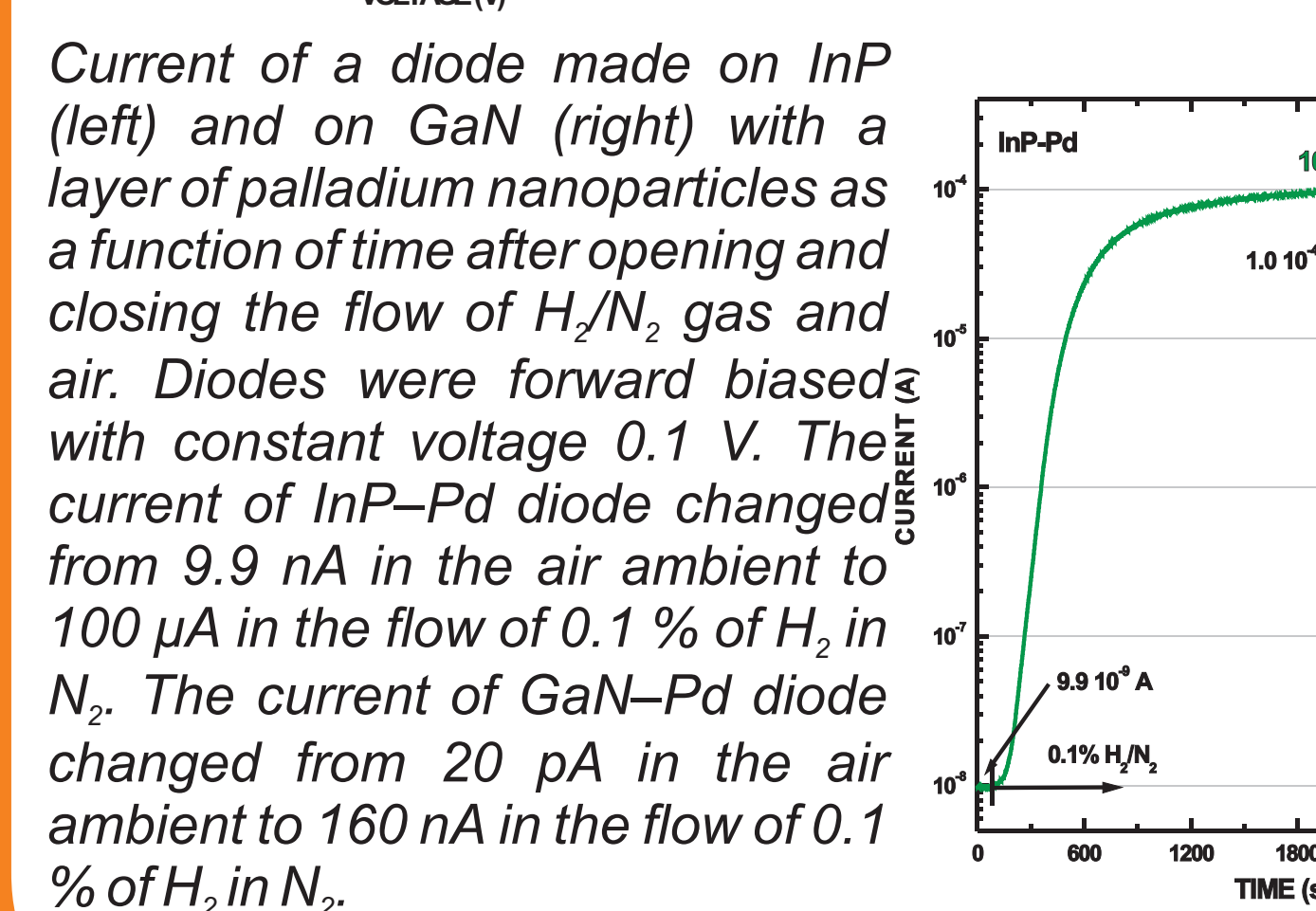


Current of a diode made on GaN with a layer of platinum nanoparticles as a function of time after opening and closing the flow of H<sub>2</sub>/N<sub>2</sub> gas and air. The diode was forward biased with constant voltage 0.1 V. The current changed from 7.4 nA in the air ambient to 540 μA in the flow of 0.1 % of H<sub>2</sub> in N<sub>2</sub>. The 50 % response time is equal to 37 s.

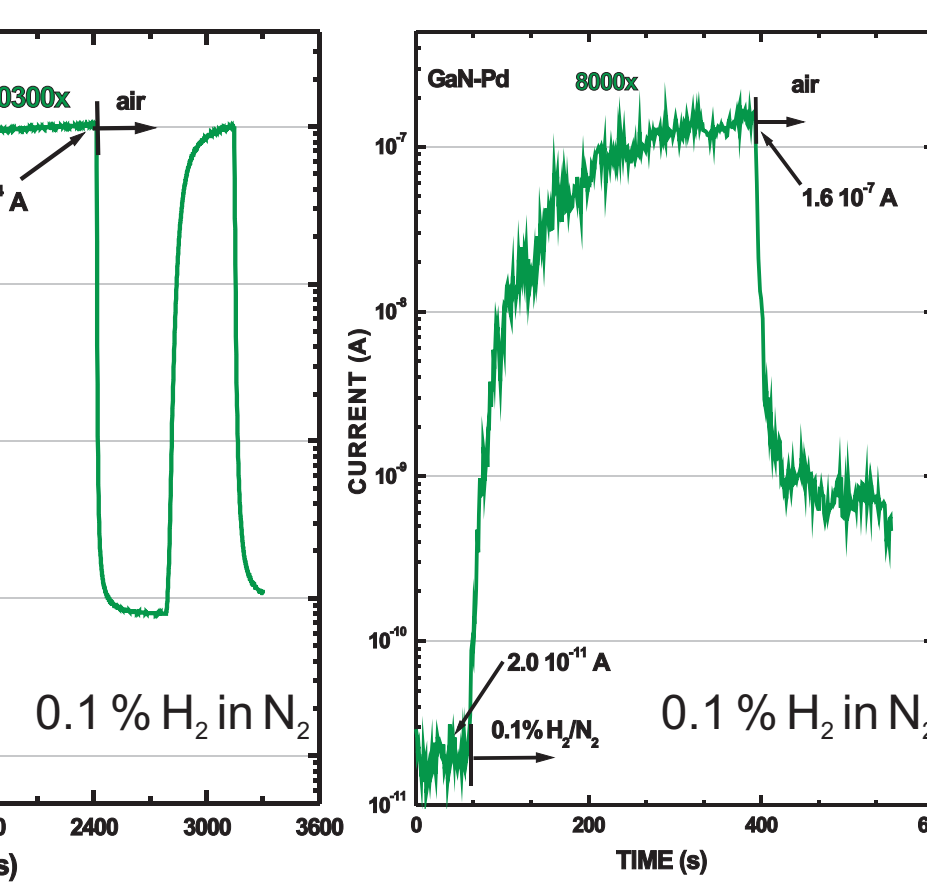


## Pd nanoparticles based structures

Forward and reverse IV characteristics of a diode fabricated on InP substrate (left diagram) and on GaN (right diagram) with a layer of palladium nanoparticles in air and hydrogen environment. Both diodes show good rectifying character both in air ambience and in hydrogen presence. The height of Schottky barrier calculated from the forward current is 0.78 eV for InP–Pd structure and 1.03 eV for GaN–Pd structure.

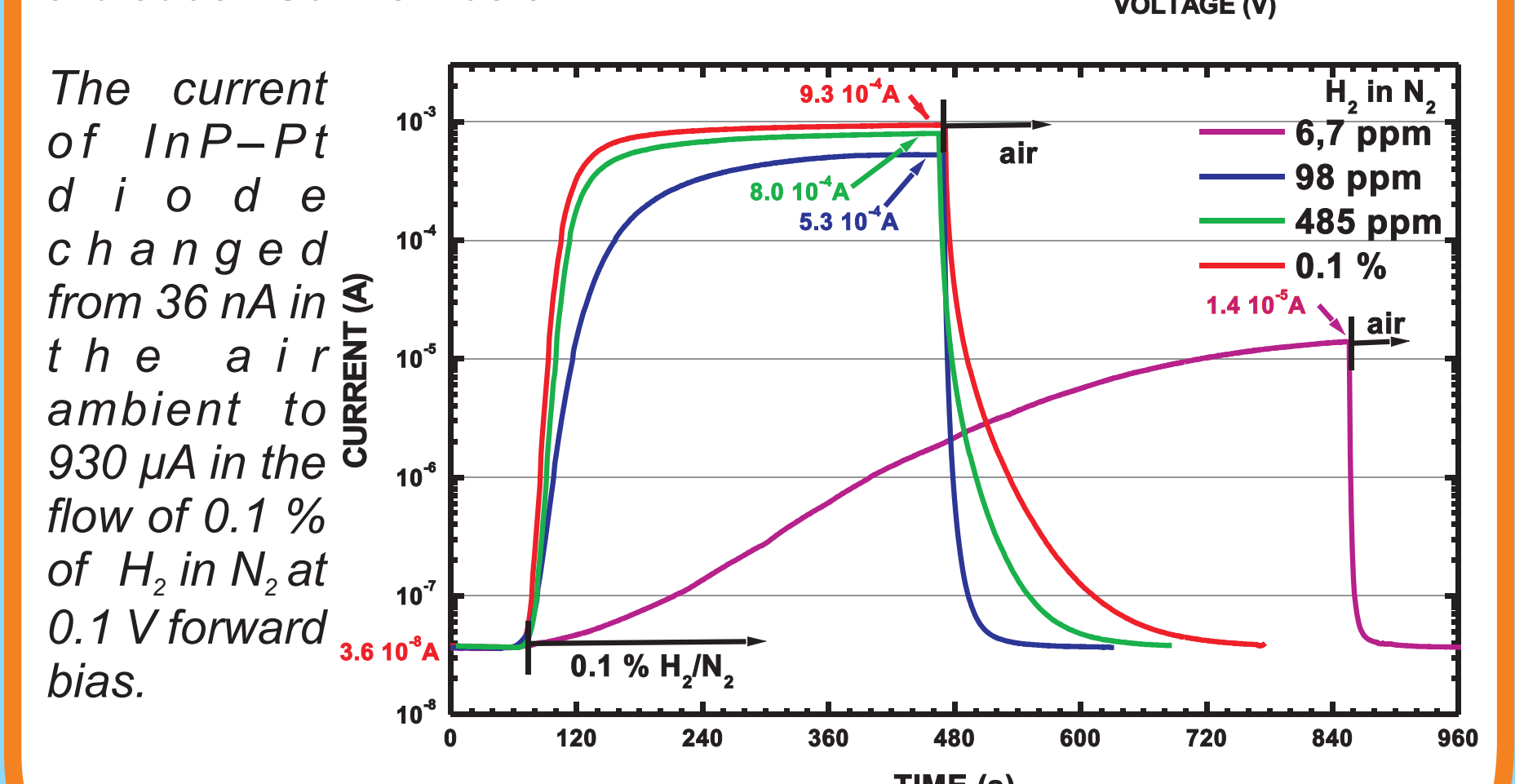


Current of a diode made on InP (left) and on GaN (right) with a layer of palladium nanoparticles as a function of time after opening and closing the flow of H<sub>2</sub>/N<sub>2</sub> gas and air. Diodes were forward biased with constant voltage 0.1 V. The current of InP–Pd diode changed from 9.9 nA in the air ambient to 100 μA in the flow of 0.1 % of H<sub>2</sub> in N<sub>2</sub>. The current of GaN–Pd diode changed from 20 pA in the air ambient to 160 nA in the flow of 0.1 % of H<sub>2</sub> in N<sub>2</sub>.



## Pt/Pd nanoparticles based structures

Forward and reverse IV characteristics of a diode fabricated on InP substrate with a layer of mixture of platinum and palladium nanoparticles in air and hydrogen environment. Diode shows good rectifying character in air ambience and low rectifying character in hydrogen presence. The height of Schottky barrier calculated from the forward current in air is 0.76 eV. Schottky barrier height on the same type of diode on GaN is 1.09 eV.



## Conclusions

- Schottky diode structure based on layers of platinum and palladium nanoparticles deposited on InP and GaN semiconductor wafers were demonstrated
- Good rectifying character of all structures, Schottky barrier higher than 1.0 eV for GaN–Pd and GaN–PtPd structures
- Fast response time and big changes in current under the flow of 0.1 % H<sub>2</sub> in N<sub>2</sub>

## Acknowledgement

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## References

- [1] H. I. Chen, Y. I. Chou and C. Y. Chu, Sens. Actuat. B85(2002) 10–18.
- [2] Y. I. Chou, C. M. Chen, W. C. Liu and H. I. Chen, IEEE Electron Device Letters 26(2005) 62–65.
- [3] K. Zdansky, P. Kacerovsky, J. Zavadil, J. Lorincik and A. Fojtik, Nanoscale Res. Lett. 2(2007) 450–455.